

### AMENDMENTS TO THE CLAIMS

Please replace all prior versions of the claims with the following claim listing:

#### ***Claims:***

1. (Currently Amended) A process for producing at least one electrical contacting pad (1) on a receiving zone (2) of an electronic component, or for regenerating a plurality of electrical contacting pads (1) produced on receiving zones (2) of an electronic component (3), in which the process comprising:

[[ - ]] injecting a liquid alloy or metal (4) ~~is injected~~ into at least one channel (5) comprising two portions, a feed portion (5A) and a molding portion (5B) which are separated by a narrowing (5C), said at least one channel (5) being positioned in such a way that the molding portion (5B) opens on the receiving zone (2);

[[ - ]] separating the molding portion (5B) ~~is separated~~ from the receiving zone (2) before complete solidification of the liquid alloy or metal ~~or alloy~~ (4), while the feed (5A) and molding (5B) portions remain joined;

~~which process is characterized in that~~ wherein the feed portion (5A) is part of a first part forming a die (6), and the molding portion (5B) is part of a separate second part forming a mold (7), said die and mold being juxtaposed to form the at least one channel (5).

2. (Currently Amended) The process as claimed in claim 1, ~~characterized in that~~ further comprising:

moving the liquid alloy or metal (4) ~~is moved~~ in the opposite direction to that of injection through the feed portion (5A), before the molding portion (5B) is separated from the receiving zone (2).

3. (Currently Amended) The process as claimed in claim 2, ~~characterized in that~~ wherein the liquid alloy or metal (4) is moved by suction.

4. (Currently Amended) The process as claimed in claim 3, ~~characterized in that~~ wherein the suction is created by the movement in the opposite direction (R) to that of injection (I) of a poppet valve-type close-off element (9) situated upstream of the channel (5) when considered in the direction of injection (I), towards a position in

which said close-off element (9) stops the supply of liquid alloy or metal (4) to the at least one channel (5).

5. (Currently Amended) The process as claimed in ~~one of claims 1 to 4,~~  
~~characterized in that the separation of~~ claim 1, wherein separating the molding portion (5B) from the receiving zone (2) takes place in a blanket of inert or reducing gas (G).

6. (Currently Amended) The process as claimed in claim 5, ~~characterized~~  
~~in that~~ wherein the gas (G) comprises nitrogen.

7. (Currently Amended) The process as claimed in claim 6, ~~characterized~~  
~~in that~~ wherein the gas (G) comprises a component containing a carboxyl group.

8. (Currently Amended) The process as claimed in claim 7, ~~characterized~~  
~~in that~~ wherein the carboxyl group-containing component is formic acid.

9. (Currently Amended) A device for producing at least one electrical contacting pad (1) on a receiving zone (2) of an electronic component (3), or for regenerating a plurality of electrical contacting pads (1) produced on receiving zones (2) on an electronic component (3), said device comprising a channel (5) for conveying liquid alloy or metal (4), said channel (5) ~~itself~~ comprising two portions, a feed portion (5A) which is part of a first part forming a die (6), and a molding portion (5B) which is part of a second part forming a mold (7), said feed (5A) and molding (5B) portions being separated by a narrowing (5C), ~~which device is characterized in that it comprises a~~ wherein the device further comprises means (10) for fixing the die (6) relative to the mold (7), allowing said die (6) and mold (7) to be juxtaposed in a fixed manner to form the channel (5).

10. (Currently Amended) The device as claimed in claim 9, ~~characterized~~  
~~in that~~ wherein the die (6) includes a plate comprising at least one porous region that forms the feed portion (5A).

11. (Currently Amended) The device as claimed in ~~claim 9 or 10~~, ~~characterized in that it comprises~~ claim 9, further comprising, upstream of the die (6) when considered in the direction of flow of the liquid alloy or metal (I), a reservoir (11) designed to contain the liquid alloy or metal (4), said reservoir (11) having a lower opening (11A) feeding into a sump (12) which communicates with said die (6), the movement of the liquid alloy or metal (4) through the lower opening being controlled by a poppet valve-type moving close-off element (9) able to move parallel to the direction of flow of the liquid alloy or metal, between an upper position in which it closes the lower opening (11A), and at least one intermediate position in which it allows the liquid alloy or metal (4) to flow through to the sump (12) and then on to the die (6).

12. (Currently Amended) The device as claimed in ~~claim 9 or 10~~, ~~characterized in that it comprises a~~ claim 9, further comprising means for dispensing a gas (G) around the molding portion.

13. (Currently Amended) The device as claimed in claim 12, ~~characterized in that~~ wherein the gas (G) is inert or reducing and comprises a component containing a carboxyl group.

14. (Currently Amended) The device as claimed in claim 13, ~~characterized in that~~ wherein the carboxyl group-containing component is formic acid.

15. (Currently Amended) The device as claimed in ~~claim 13 or 14~~, ~~characterized in that~~ claim 13, wherein the gas (G) includes nitrogen.

16. (Currently Amended) The device as claimed in ~~one of claims 13-15~~, ~~characterized in that~~ claim 13, wherein the gas (G) dispensing means comprises [[a]] diffusion means and, situated upstream of said diffusion means, [[a]] production means, said diffusion means allowing the carboxyl group-containing component to be imbibed by a primary inert or reducing gas.

17. (Currently Amended) The device as claimed in ~~one of claims 9-16,~~  
~~characterized in that~~ claim 9, wherein the channel (5) is designed to be positioned  
above the receiving zone (2).